

Lenovo System x3100 M5 server (5457C3G)

1 x Xeon E3-1231 v3, 4GB (DDR3), 4 x 3.5" HDD, DVD-ROM, RAID 0/1, 300W



Price details:

Price excl. VAT: 852.75 €

Eco fees: 0.08 €

VAT 21 %: 179.09 €

Product details:

Product code: 5457C3G

EAN: 4053162449992

Manufacturer: Lenovo

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1,031.92 €

* VAT included

Highlights

- Delivers new performance capabilities, powered by the latest Intel processors and energy-saving low-voltage memory
- Safeguards and boosts your growing business with hard drive hot-swap capabilities, 1 40°C operating temperature enhancement kit, 2 four PCIe slots, storage choices, and flexible options
- Offers built-in data protection with up to four RAID levels and reliability you expect from System x®
- New performance capabilities, powered by the latest Intel processors (choice of Intel Xeon E3-1200 v3, Core i3, Pentium, or Celeron)
- Energy-saving low-voltage memory
- Upgradable operating temperature (up to 40°C) with optional temperature enhancement kit for optimized energy efficiency
- Built-in data protection with up to four RAID levels and reliability you expect from System x®: Standard ServeRAID-0, -1, -10, plus RAID-5 available via Feature on Demand
- Flexible storage options for up to 24 TB of capacity: 4 x 3.5-inch or 8 x 2.5-inch hard disk drives (HDDs), plus hot-swap options for minimized downtime
- USB 3.0 for up to 10x faster data transfer
- Graphics processor: NVIDIA K600 GPU available for graphics support
- Compact mini 4U design or flexible 5U for redundant, energy-smart 80 PLUS® Silver power supply
- The new single-socket System x3100 M5 server provides business-class reliability and performance in a compact tower, optimized for small to medium-sized businesses and distributed environments. Equipped with the latest Intel® Xeon® E3-1200 v3 processors, USB 3.0 for fast data transfer, 1.35 V low-voltage memory for power savings, 3.5-inch hot-swap SAS hard disk drives (HDDs) for minimized downtime, and four levels of RAID for enhanced data protection, the x3100 M5 brings new levels of performance to your workloads while maximizing energy savings. This efficient tower meets your business needs today and offers upgrade potential when your requirements grow.

Reliability and performance in a flexible, compact tower server

Whether your workloads include basic infrastructure, web server, or file and print, the x3100 M5 delivers. Choose your storage preference from models with four 3.5-inch simple-swap HDD bays, or get the hot-swap versatility of eight 2.5-inch bays or four 3.5-inch hot-swap bays. Standard features include capacity for up to 32 GB of memory, two Gigabit Ethernet ports, and two front-mounted fast USB 3.0 ports, plus multiple internal and external USB 2.0 connections. Business-class reliability features—such as standard RAID, basic light path diagnostics, and optional redundant power supplies and fans—protect your data and facilitate outstanding uptime for your business at great value. Select configurations of the x3100 M5 are part of the Express Portfolio, designed to meet the needs of small and midsized businesses. Easy to manage, Express models vary by country.

Main specifications:

Processor

Processor frequency:	3.4 GHz
Processor family:	Intel Xeon E3 v3
Processor model:	E3-1231V3
Processor cores:	4
Number of processors installed:	1

Processor cache type:	Smart Cache
Processor cache:	8 MB
System bus rate:	5 GT/s
Processor manufacturer:	Intel
Compatible processor series:	Xeon
Processor socket:	LGA 1150 (Socket H3)
Motherboard chipset:	Intel C222
Processor boost frequency:	3.8 GHz
Processor lithography:	22 nm
Processor threads:	8
Processor operating modes:	32-bit,64-bit
Stepping:	C0
FSB Parity:	N
Bus type:	DMI2
Processor codename:	Haswell
Maximum internal memory supported by processor:	32 GB
Memory types supported by processor:	DDR3-SDRAM
Memory clock speeds supported by processor:	1333,1600 MHz
Memory bandwidth supported by processor (max):	25.6 GB/s
Memory channels supported by processor:	Dual
ECC supported by processor:	Y
Execute Disable Bit:	Y
Idle States:	Y
Thermal Monitoring Technologies:	Y
Maximum number of PCI Express lanes:	16
PCI Express configurations:	1x16,2x8,1x8+2x4
Processor package size:	37.5 mm
Supported instruction sets:	AVX 2.0,SSE4.1,SSE4.2
Scalability:	1S
Embedded options available:	N
Thermal solution specification:	PCG 2013D
Graphics & IMC lithography:	22 nm
Thermal Design Power (TDP):	80 W
Processor series:	Intel Xeon E3-1200 v3
Conflict Free processor:	N

Memory

Internal memory:	4 GB
Internal memory type:	DDR3-SDRAM
Maximum internal memory:	32 GB
Memory slots:	4 x DIMM
Memory clock speed:	1600 MHz
ECC:	Y
Memory layout (slots x size):	1 x 4 GB

Storage

Hard drive size:	3.5 "
Hard drive interface:	Serial ATA
RAID support:	Y
Maximum storage capacity:	12 TB
RAID levels:	0,1
Number of hard drives supported:	4
Internal drive bays:	4

Graphics

Maximum graphics adapter memory:	16 MB
On-board graphics adapter:	N
On-board graphics adapter model:	Not available

Networking

Ethernet LAN:	Y
Cabling technology:	10/100/1000Base-T(X)
Ethernet interface type:	Gigabit Ethernet

Ports & interfaces

USB 2.0 ports quantity:	4
VGA (D-Sub) ports quantity:	1
Ethernet LAN (RJ-45) ports:	2
Serial ports quantity:	1
USB 3.0 (3.1 Gen 1) Type-A ports quantity:	2

Expansion slots

PCI Express x4 (Gen 2.x) slots:	1
PCI Express x8 (Gen 2.x) slots:	1
PCI Express x8 (Gen 3.x) slots:	1
PCI Express x16 (Gen 3.x) slots:	1
PCI Express slots version:	3.0

Design

Chassis type:	Tower (4U)
Optical drive type:	DVD-ROM

Performance

Operating system installed:	N
Compatible operating systems:	Microsoft Windows Server 2012/2008/R2, SBS 2011, Red Hat Enterprise Linux, SUSE Linux, VMware
BIOS type:	UEFI
Trusted Platform Module (TPM):	Y
Trusted Platform Module (TPM) version:	1.2

Processor special features

Intelligent Platform Management Interface (IPMI) support:	
CPU configuration (max):	1
Intel Rapid Storage Technology:	N
Enhanced Intel SpeedStep Technology:	Y
Intel® Identity Protection Technology (Intel® IPT):	Y
Intel® Wireless Display (Intel® WiDi):	N
Intel Virtualization Technology for Directed I/O (VT-d):	Y
Intel® Anti-Theft Technology (Intel® AT):	Y
Intel® Hyper Threading Technology (Intel® HT Technology):	Y
Intel® My WiFi Technology (Intel® MWT):	N
Intel® Turbo Boost Technology:	2.0
Intel® vPro® Technology:	Y
Intel® Quick Sync Video Technology:	N
Intel® InTru® 3D Technology:	N
Intel® Clear Video HD Technology (Intel® CVT HD):	Y
Intel® Insider®:	N
Intel Flex Memory Access:	Y
Intel® Smart Cache:	Y
Intel® AES New Instructions (Intel® AES-NI):	Y
Intel Trusted Execution Technology:	Y
Intel Enhanced Halt State:	Y
Intel VT-x with Extended Page Tables (EPT):	Y
Intel Demand Based Switching:	N
Intel® Secure Key:	Y
Intel Stable Image Platform Program (SIPP):	Y
Intel Clear Video Technology:	N
Intel® Clear Video Technology for Mobile Internet Devices (Intel CVT for MID):	Y
Intel 64:	Y
Intel Identity Protection Technology version:	1.00
Intel Stable Image Platform Program (SIPP) version:	1.00
Intel Secure Key Technology version:	1.00
Intel Virtualization Technology (VT-x):	Y
Intel TSX-NI version:	1.00
Intel Dual Display Capable Technology:	N
Intel FDI Technology:	N
Intel I/O Acceleration Technology:	Y
Intel Fast Memory Access:	Y
Processor ARK ID:	80910

Power

Redundant power supply (RPS) support:	Y
Power supply:	300 W
Number of main power supplies:	1

Weight & dimensions

Width:	180 mm
Depth:	480 mm
Height:	360 mm
Weight:	13000 g

Other features

Graphics adapter: G200eR2
Graphics adapter family: Matrox
Intel® Virtualization Technology (Intel® VT): VT-d,VT-x

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